

DOCKET NO: 248983US2DIV

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF :  
MICHIAKI HIYOSHI : ATTN: APPLICATION DIVISION  
SERIAL NO: NEW U.S. PCT APPLN. :  
(Based on 09/917,876)  
FILED: HERewith :  
FOR: HERMETICALLY SEALED :  
SEMICONDUCTOR POWER  
MODULE AND LARGE SCALE  
MODULE COMPRISING THE  
SAME

PRELIMINARY AMENDMENT

COMMISSIONER FOR PATENTS  
ALEXANDRIA, VIRGINIA 22313

SIR:

Prior to examination on the merits, please amend the above-identified application as follows:

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page of this paper.

**Remarks/Arguments** begin on page 11 of this paper.